

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claim 1 (currently amended): A semiconductor light emitting device comprising:

an active layer composed of a nitride based semiconductor;

a cladding layer formed on said active layer, composed of a nitride based semiconductor of a first conductivity type, and having a flat portion and a ridge portion formed on the flat portion;

a first current blocking layer formed on said flat portion and on sidewalls of said ridge portion of said cladding layer and composed of a high-resistive nitride based semiconductor containing impurities; and

a second current blocking layer formed on said first current blocking layer and composed of a nitride based semiconductor of a second conductivity type opposite to said first conductivity type:

wherein the cladding layer is composed of AlGaN;

wherein the first current blocking layer is composed of AlGaN having a larger Al composition ratio than that of the cladding layer; and

wherein said impurities contain at least one of zinc, beryllium, calcium, and carbon;

~~a second current blocking layer formed on said first current blocking layer and~~

~~composed of a nitride based semiconductor of a second conductivity type opposite to said first conductivity type;~~

~~wherein the cladding layer is composed of AlGaIn;~~

~~wherein the first current blocking layer is composed of AlGaIn having a larger Al composition ratio than that of the cladding layer; and~~

~~wherein said impurities contain at least one of zinc, beryllium, calcium, and carbon.~~

Claim 2 (canceled)

Claim 3 (original): The semiconductor light emitting device according to claim 1, wherein said first current blocking layer has a resistance value of not less than  $1.5 \Omega \cdot \text{cm}$

Claim 4 (canceled)

Claim 5 (original): The semiconductor light emitting device according to claim 1, wherein the thickness of said first current blocking layer is not less than  $0.5 \mu\text{m}$ .

Claim 6 (original): The semiconductor light emitting device according to claim 5, wherein the thickness of said first current blocking layer is not less than  $1.0 \mu\text{m}$ .

Claim 7 (original): The semiconductor light emitting device according to claim 1, wherein the thickness of the flat portion of said cladding layer is not more than 0.3  $\mu\text{m}$ .

Claim 8 (currently amended): The semiconductor light emitting device according to claim 7, ~~wherein~~ wherein the thickness of the flat portion of said cladding layer is not more than 0.08  $\mu\text{m}$ .

Claim 9 (original): The semiconductor light emitting device according to claim 1, wherein said nitride based semiconductor contains at least one of boron, gallium, aluminum, indium, and thallium.

Claim 10 (currently amended): ~~[[A]]~~ The semiconductor light emitting device according to claim 1, wherein comprising:

~~an active layer composed of a nitride based semiconductor;~~

~~a cladding layer formed on said active layer, composed of a nitride based semiconductor of a first conductivity type, and having a flat portion and a ridge portion formed on the flat portion, said cladding layer having a recess on said flat portion along both sidewalls of said ridge portion; and~~

~~[[a]] said first current blocking layer is formed on said flat portion and on the sidewalls of said ridge portion of said cladding layer and composed of a high resistive nitride based semiconductor containing impurities such that it is embedded in said recess of said cladding layer;~~

and

~~a second current blocking layer formed on said first current blocking layer and composed of a nitride based semiconductor of a second conductivity type opposite to said first conductivity type;~~

~~wherein the cladding layer is composed of AlGa<sub>0.3</sub>N<sub>0.7</sub>; and~~

~~wherein the first current blocking layer is composed of AlGa<sub>0.3</sub>N<sub>0.7</sub> having a larger Al composition ratio than that of the cladding layer;~~

~~wherein said first current blocking layer is composed of a high resistive nitride based semiconductor containing impurities; and~~

~~wherein said impurities contain at least one of zinc, beryllium, calcium, and carbon.~~

Claims 11-19 (canceled)